

**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10038806	01/02/2002	257		2811	S. VU

****APPLICANTS:** Takeuchi Timothy;

****CONTINUING DATA VERIFIED:**

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**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 42P13557
Verified and Acknowledged Examiner's initials			
TITLE : Semiconductor package with integrated heat spreader attached to a thermally conductive substrate core			
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claims for O.G.
Assistant Examiner		DRAWING	
Amount Due	Date Paid	Sheets Drawn	Figures Drawn
Primary Examiner		Print File	
TERMINAL		Application Examiner	
DISCLAIMER		PREPARED FOR ISSUE	
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